



Designing new ultra-radiopure, high-strength electroformed Cu-based alloys, for rare event searches

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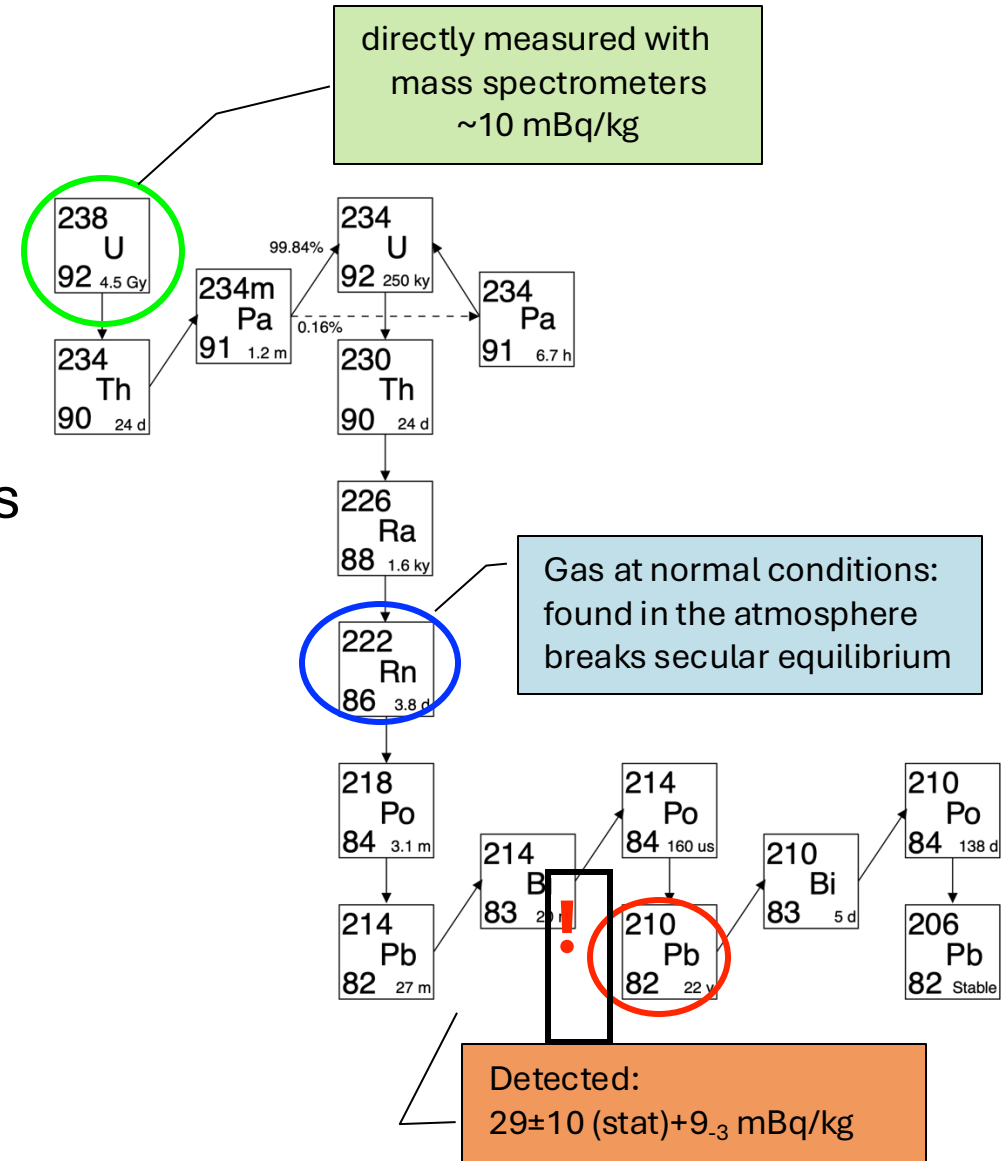


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Radiopure **Cu** for rare event searches

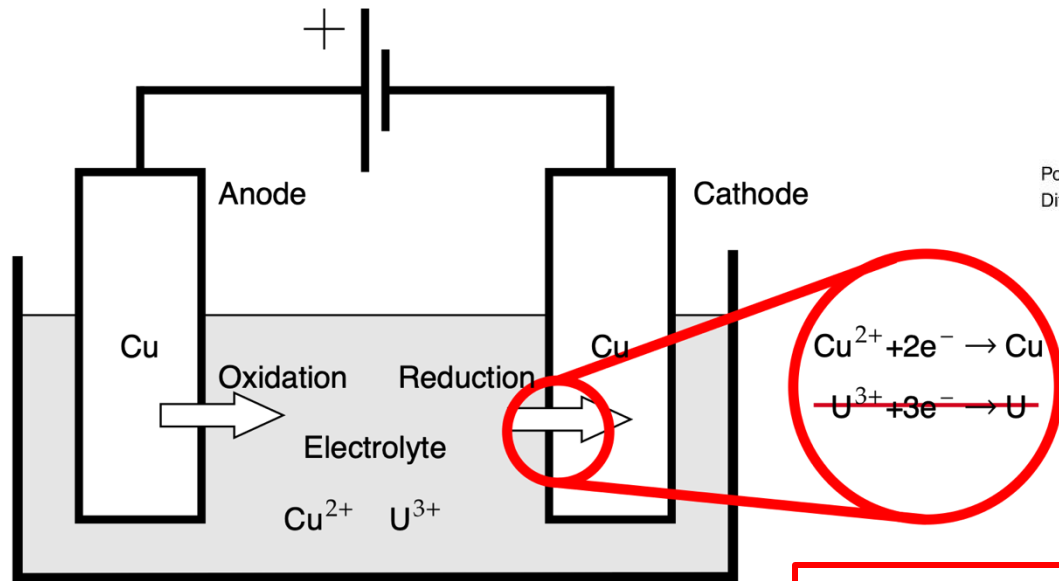
- Cu: common material for rare event searches experiments
 - ✓ Electrically conductive
 - ✓ Strong enough to build low-pressure gas vessels
 - ✓ No long-lived isotopes (^{67}Cu $t_{1/2}=62\text{h}$)
 - ✓ Low cost/commercially available at high purity
- Backgrounds
 - ✓ Cosmogenic: $^{63}\text{Cu}(n,\alpha)^{60}\text{Co}$ from fast neutrons
 - ✓ Contaminants: $^{238}\text{U}/^{232}\text{Th}$ decay chains



Electroformed Cu (EFCu) for rare event searches

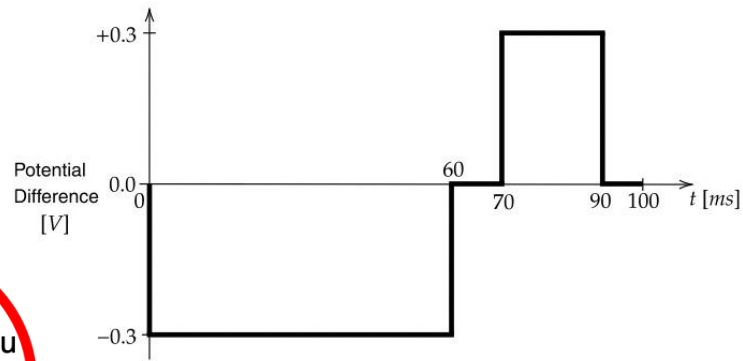
Reduction potential for copper and possible radiocontaminants.

Reductants		Oxidants	E^0 (V)
$\text{Cu}^{2+} + 2e^-$	\rightleftharpoons	Cu	+0.34
$\text{Pb}^{2+} + 2e^-$	\rightleftharpoons	Pb	-0.13
$\text{U}^{3+} + 3e^-$	\rightleftharpoons	U	-1.80
$\text{Th}^{4+} + 4e^-$	\rightleftharpoons	Th	-1.90
$\text{K}^+ + e^-$	\rightleftharpoons	K	-2.93



Giovanni Rogers
Poster/ 136

rare event searches:
e.g. LEGEND, NEWS-G,
ANAIS, Majorana, nEXO
DarkSPHERE

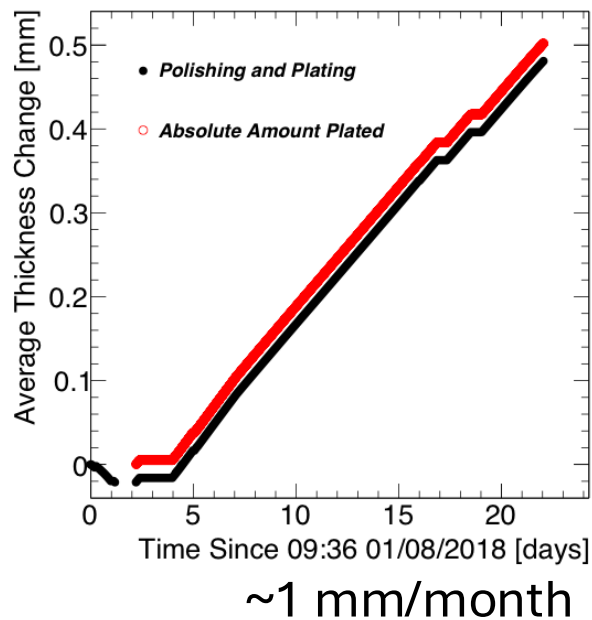


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Cu 'High reduction potential'
→ Preferentially deposited → Additive-free, electroforming

Ultra-pure Cu electroforming

Majorana Demonstrator

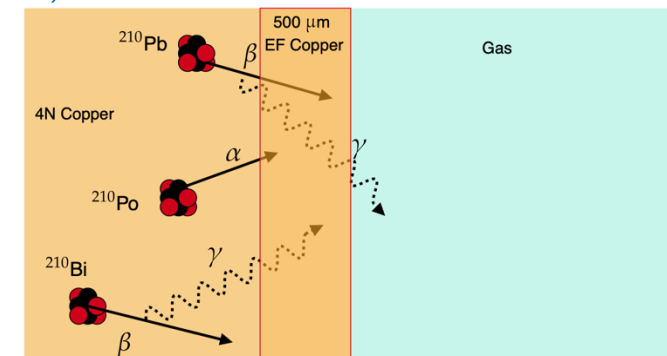


#	Material	Method	K (10^{-9} g/g)	^{232}Th (10^{-12} g/g)	^{238}U (10^{-12} g/g)
<i>Metals</i>					
1	Cu Electroformed Stock Sample	ICPMS		<0.17	
2	Cu Electroformed Stock Sample	ICPMS		0.011±0.005	0.017±0.003
3	Cu Electroformed Stock Sample	GDMS	<2.2	<50	<70
4	Cu Electroformed Stock Sample	ICPMS		<0.029	<0.008
5	Cu Electroformed Stock Sample	ICPMS		<0.029	<0.009
6	Cu Electroformed Stock Sample	ICPMS		<0.029	<0.008
7	Cu Electroformed Stock Sample	ICPMS		<0.030	<0.009
8	Cu Electroformed, machined part, guide clip	ICPMS		0.330 ± 0.022	0.123 ± 0.005
9	Cu Electroformed, machined part, guide clip	ICPMS		0.112 ± 0.009	0.078 ± 0.002
10	Cu Electroformed, machined part, guide clip	ICPMS		0.170 ± 0.008	0.087 ± 0.002
11	Cu Electroformed, machined part, spring clip	ICPMS		0.215 ± 0.009	0.130 ± 0.010
12	Cu Electroformed, machined part, hex bolt	ICPMS		0.118 ± 0.011	0.035 ± 0.004
13	Cu Electroformed, machined part, hex bolt	ICPMS		0.119 ± 0.014	0.041 ± 0.003
14	Cu Electroformed, machined part, hex bolt	ICPMS		0.148 ± 0.021	0.051 ± 0.002
15	Cu, C10100 cake stock, (source for Rows 16,17)	ICPMS		0.46 ± 0.06	0.21 ± 0.06
16	Cu, C10100 2.5" plate stock, exterior sample	ICPMS		0.27±0.05	0.10±0.02
17	Cu, C10100 2.5" plate stock, interior sample	ICPMS		0.27±0.05	0.12±0.02
18	Cu, C10100 1" plate stock, saw cut (same stock Row 19)	ICPMS		10.2 ± 1.0	6.62 ± 0.58
19	Cu, C10100 1" plate stock, machined surfaces	ICPMS		1.88 ± 0.45	3.11 ± 0.39
20	Cu, C10100 1" x 2" bar stock, machined surfaces	ICPMS		2.12 ± 0.39	2.25 ± 0.15
21	Cu, C10100 1" plate stock	ICPMS		<0.029	0.013 ± 0.002
22	Cu, C10100 2.5" plate stock	ICPMS		<0.030	0.017 ± 0.003
23	Cu, C10100 2.5" plate stock	ICPMS		0.049 ± 0.010	0.061 ± 0.006
24	Cu, C10100 0.5" plate stock	ICPMS		<0.030	0.009 ± 0.001

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- ✓ 500 μm electroplated layer to NEWS-G detector inner surface
- ✓ Demonstrated potential to electroform full detector on feasible time scale

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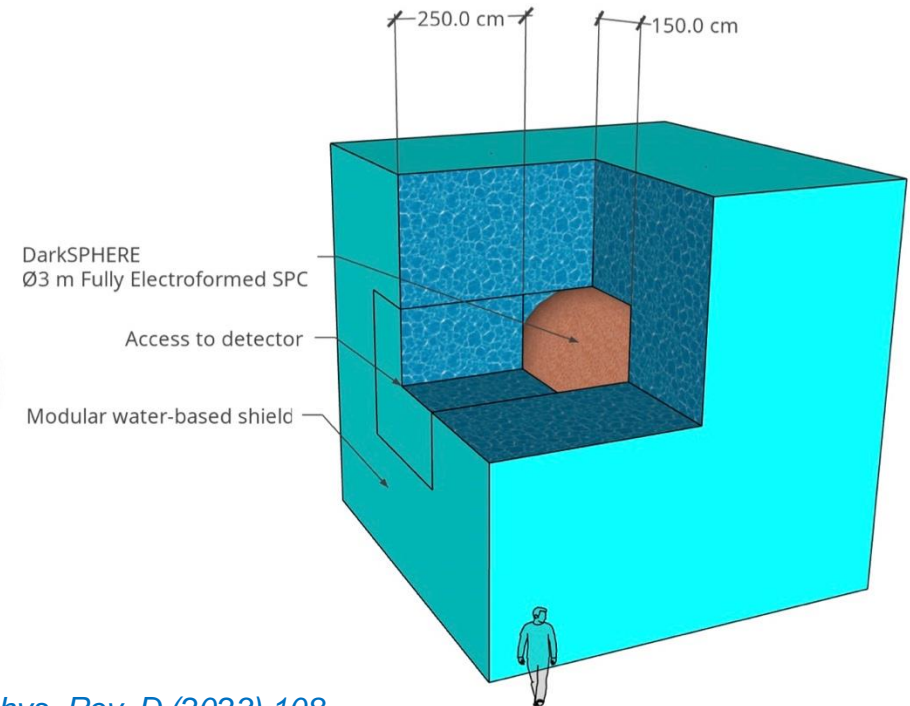
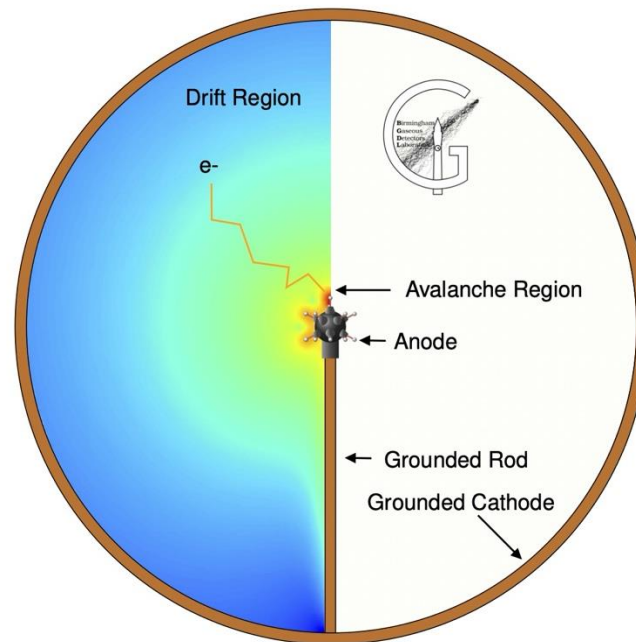


Motivation of ultra-pure, high-strength Cu-based alloys

- ✓ Retain EFCu capabilities for rare event searches
- ✓ Option for stronger material compared to Cu
- ✓ Scale up the current geometries for gas vessels
(i.e. maximising the physics potential in DM experiments)

fundamental science
applications:
e.g. nEXO, NEXT,
DarkSPHERE

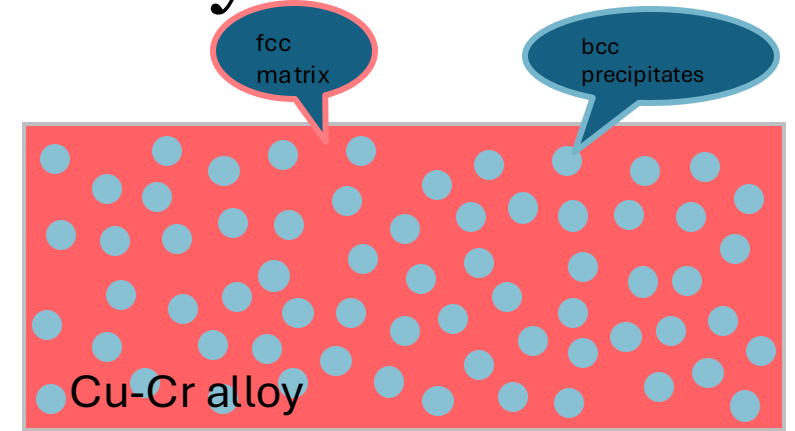
- other applications
(**not radiopure**):
- Electronic circuits
 - Storage technology



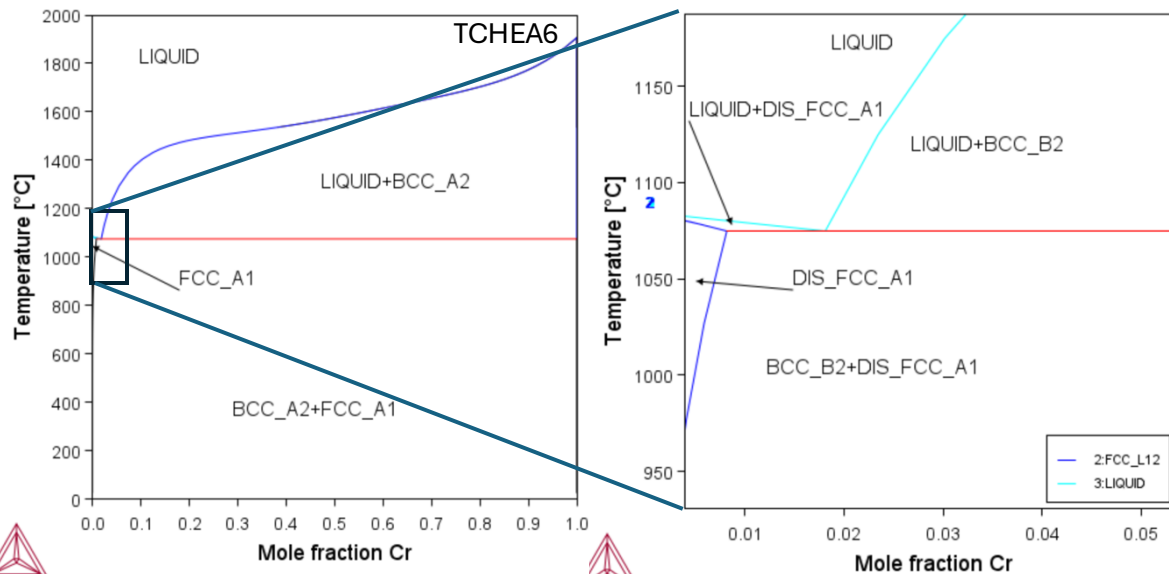
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Strengthening mechanisms in CuCr alloys

- ✓ retain Cu electrical conductivity
- ✓ stronger than Cu
- ✓ radiopure



DICTRA or TC-PRISMA : TCHEA6-MOBHEA3 (TC High Entropy Alloys database)

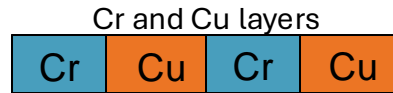


- Solution heat treatment (homogenisation)
1025°C - 1050°C
- Precipitation strengthening (aging)
400°C - 500°C

Alloying EFCu with Cr additions

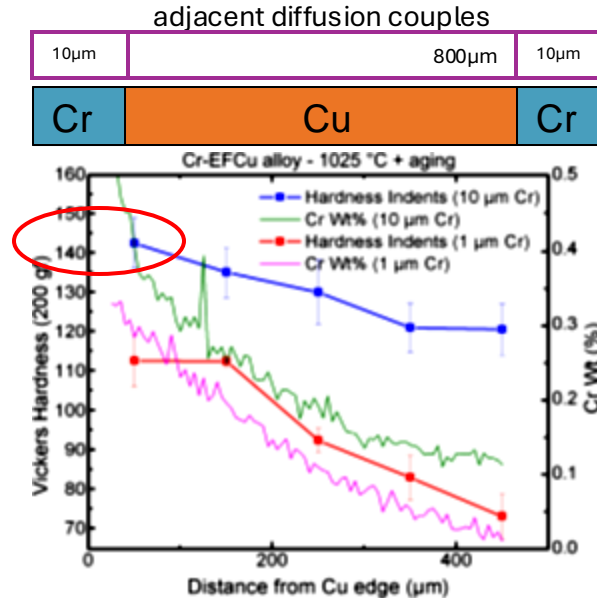
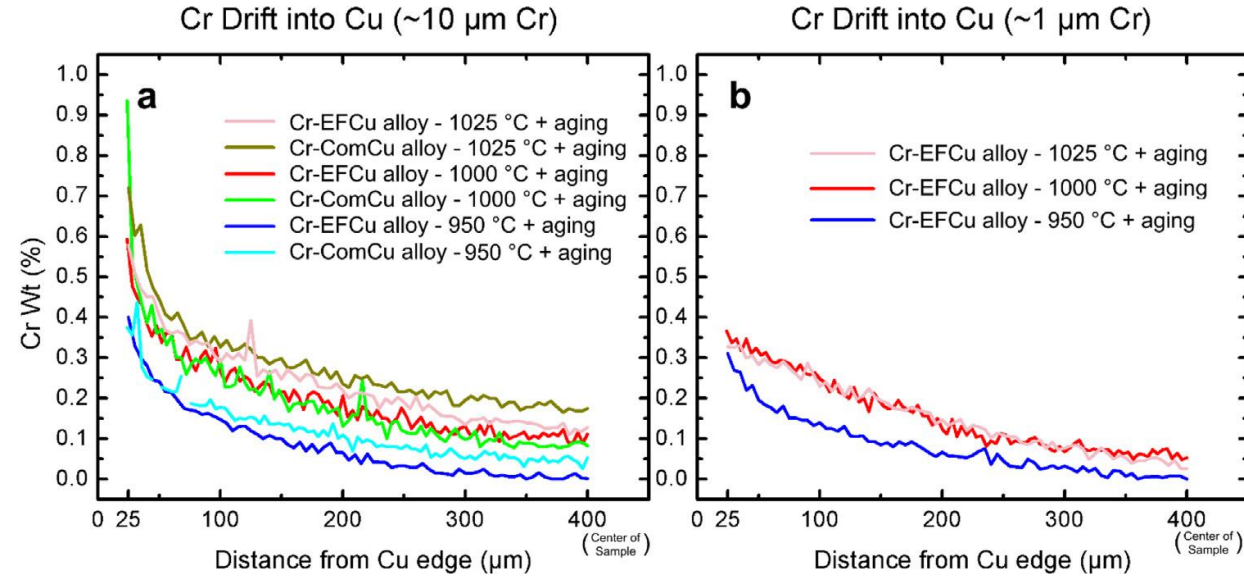
1. Cr and Cu layers from separate solutions
2. Solution heat treatment at **1000°C** (homogenisation)
3. Aging at **400°C – 12 hours** (precipitation strengthening)

Sample	[Th]		[U]	
	pgTh/gSample	±sd	pgU/gSample	±sd
EFCu	0.011	0.005	0.017	0.003
Cr	8.72	0.32	2.37	0.61
Cu-Cr(0.585wt%) projection	0.062	0.007	0.031	0.007

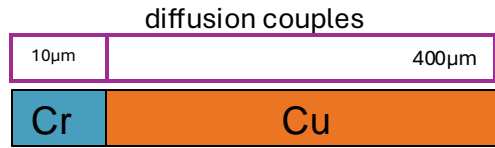


**~70%
harder**

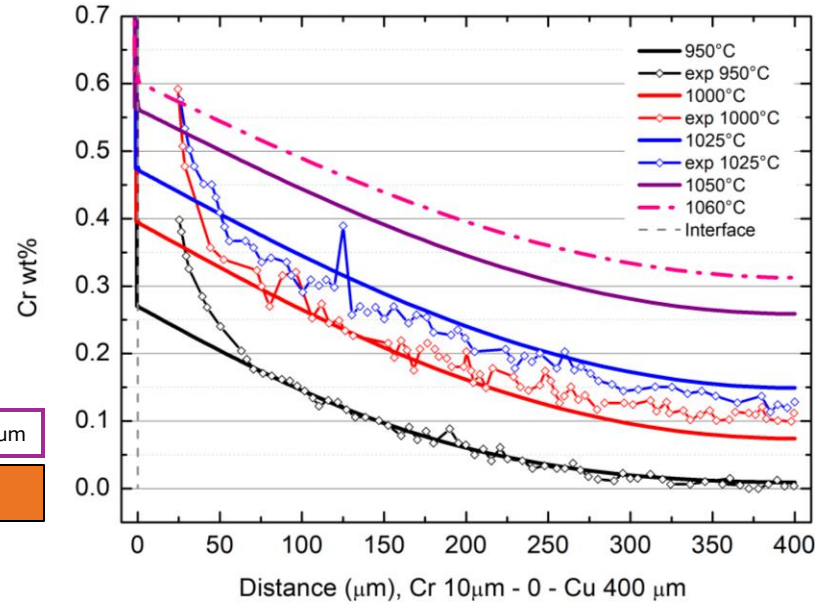
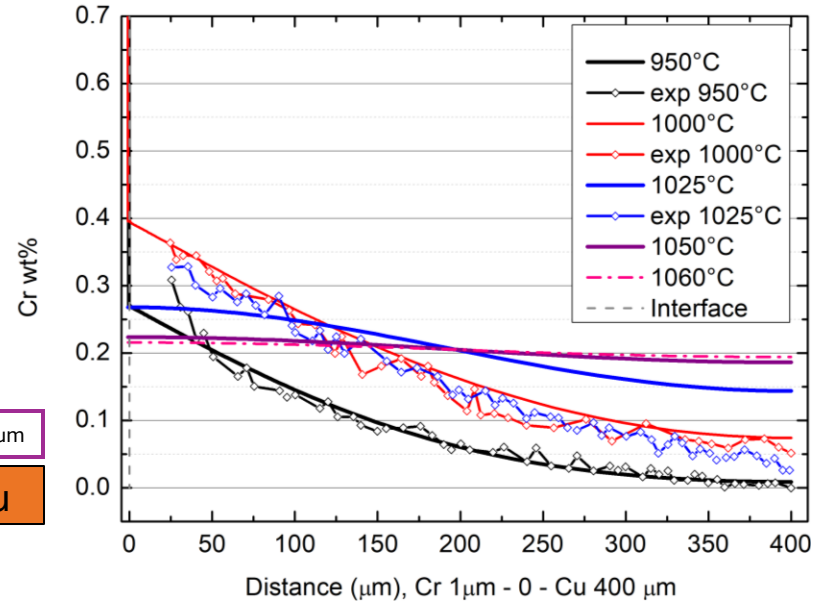
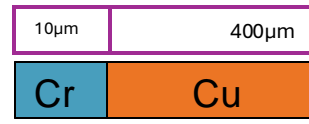
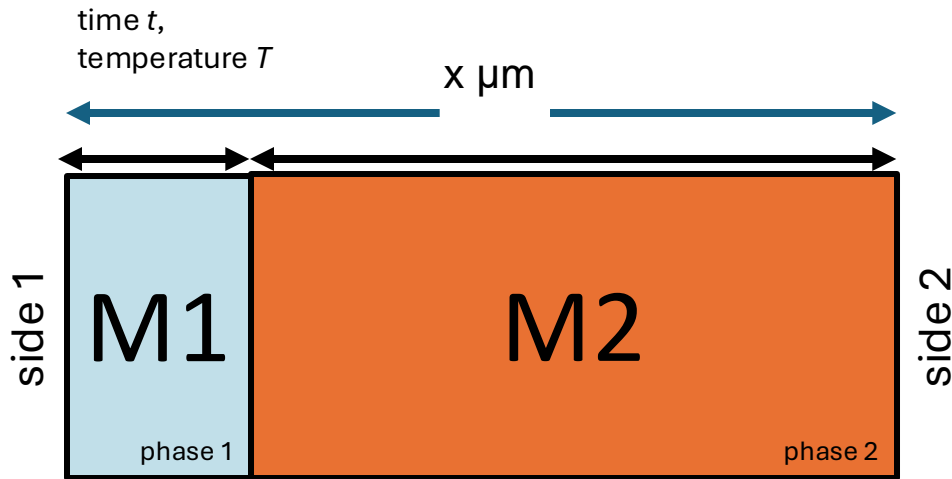
EFCu	72 HV
Cu-0.585Cr	121 HV



Modelling solution heat treatment



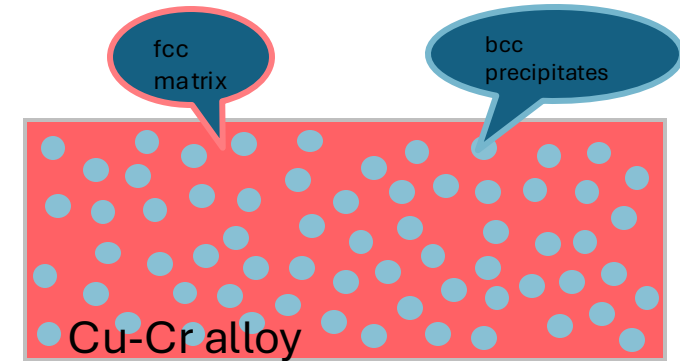
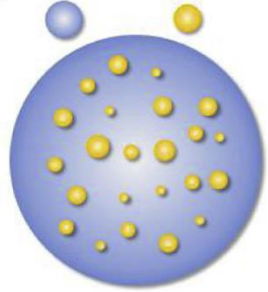
Predict t and T for solution heat treatment



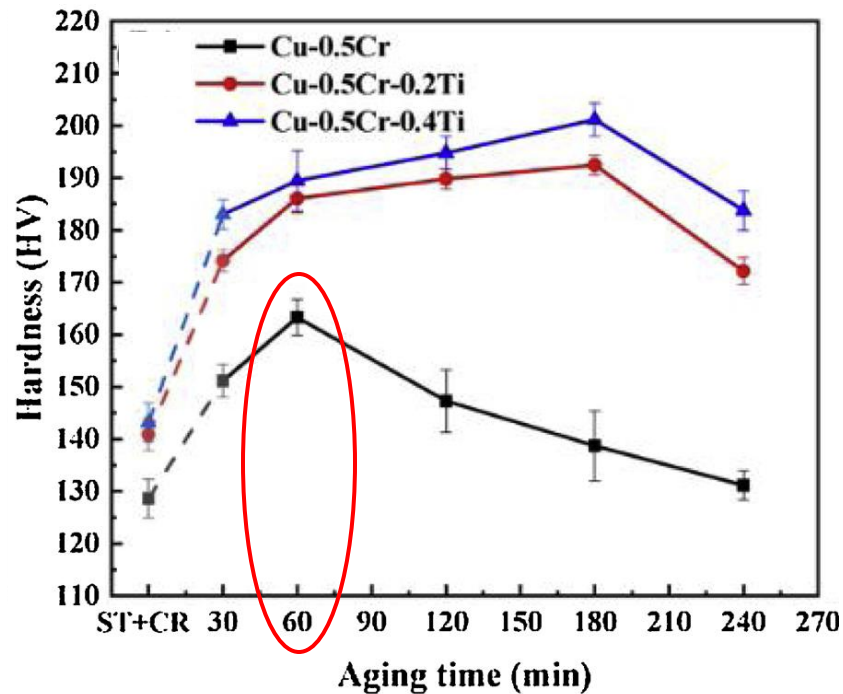
Modelling precipitation strengthening

Predict t and T for aging

Cu_matrix Cr_particle



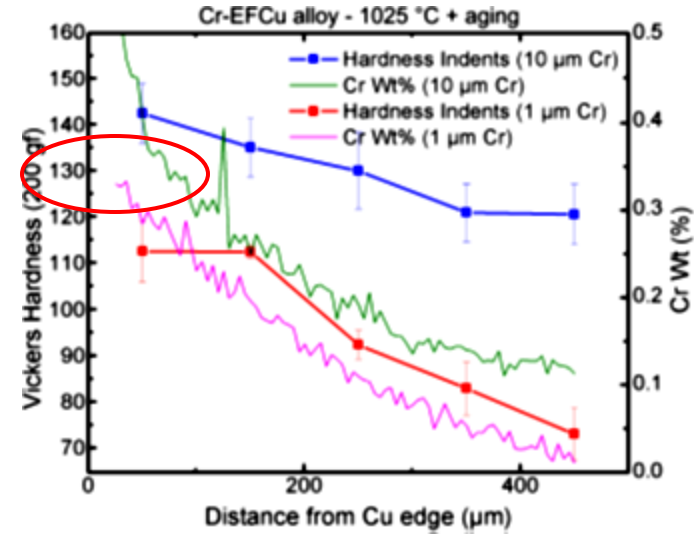
450°C – 60 min



Cu-0.5Cr	150 HV
Cu-0.5Cr0.2Ti	230 HV
Cu-0.5Cr0.4Ti	280 HV

Huang et. Al 2021

500°C – 12 hours



Cu-0.4Cr	140 HV
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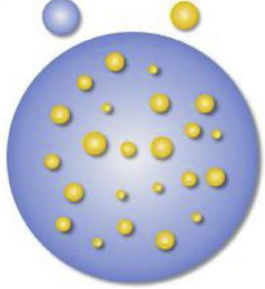
Vitale et al. 2021

EFCu	72 HV
Cu-0.585Cr	121 HV

Suriano et. al. 2018

Optimising aging parameters

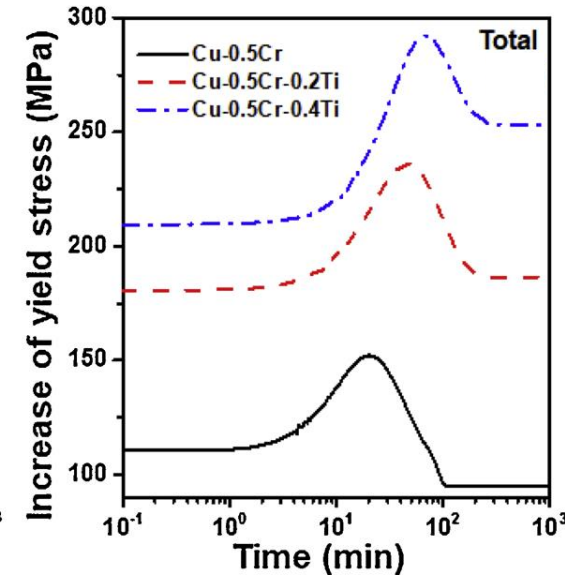
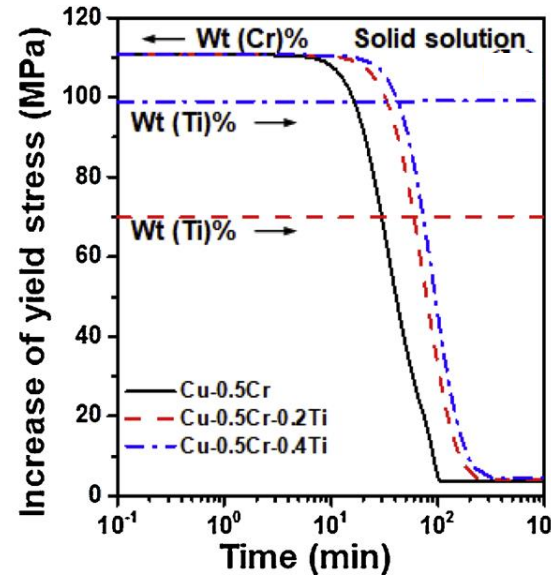
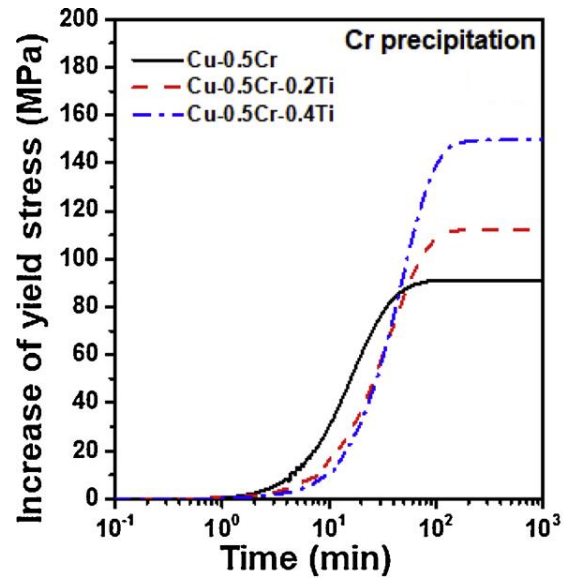
Cu_matrix Cr_particle



Prior aging @450°C:

Solution heat treatment (as-cast) – cold work (90% total deformation)

Interfacial energy: 0.68 - 0.72 J/m²



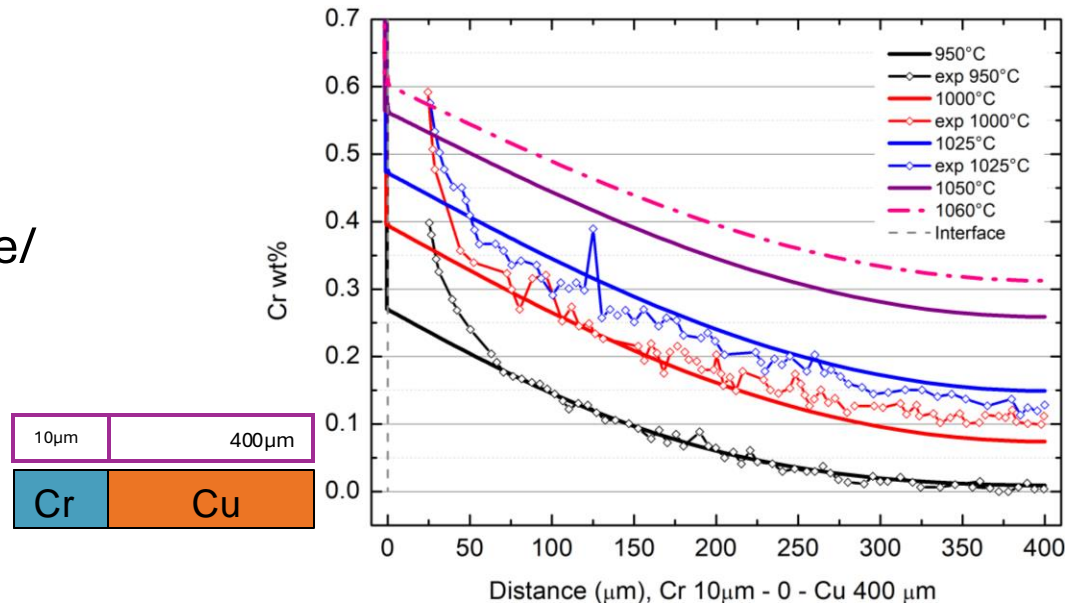
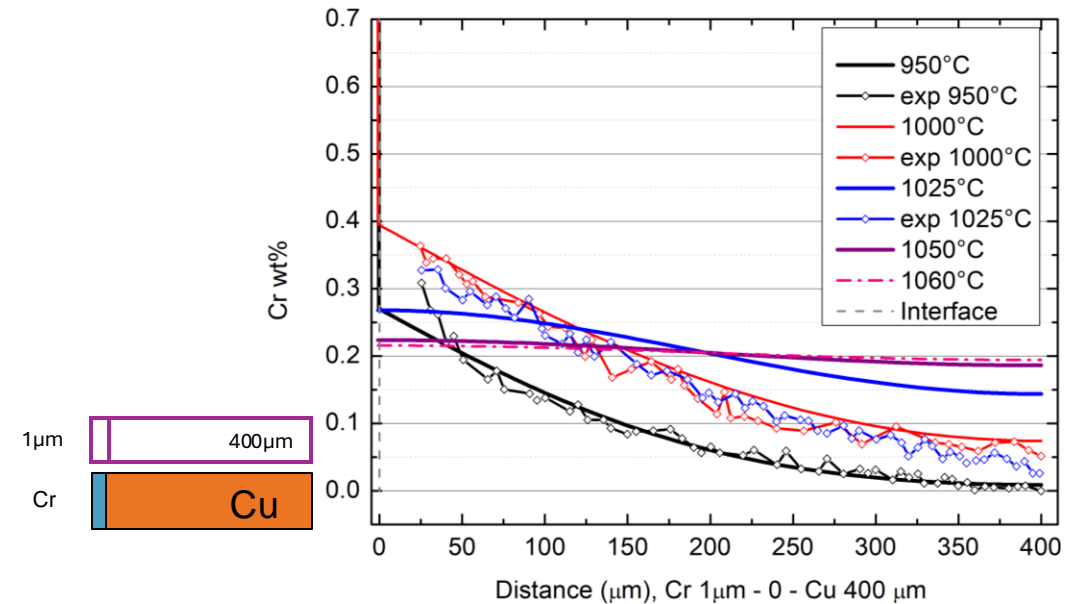
Cu-0.5Cr aging at 450°C for 60min → peak strength

Outputs (temporal evolution) for Yield strength:

- ✓ radius precipitate (nm)
- ✓ Volume fraction % precipitate
- ✓ Cr concentration in matrix

Conclusions

- ✓ Radiopure materials are extremely important for rare event searches experiments
- ✓ Cu is the material of choice, but enhanced mechanical properties are required
- ✓ Cu-based alloys are suggested as promising alternative
- ✓ Based on early experimental trials, synthesis of Cu-based alloys is possible during electrodeposition
- ✓ Solution heat treatment simulations validated – aging time/ duration needs to be explored further with experiments
- ✓ Modelling tools are available to study and optimise the process, with confirmed findings as a starting point



Thank you for your attention!

focusing on
ultra-radiopure, high strength **Cu**-based alloys

